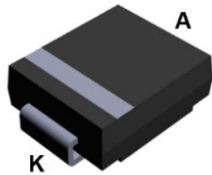
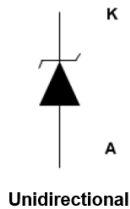


## 5000 W TVS in SMC



SMC  
(JEDEC DO-214AB)



## Features

- Peak pulse power:
  - 5000 W (10/1000  $\mu$ s)
  - up to 48 kW (8/20  $\mu$ s)
- Stand-off voltage range from 5 V to 100 V
- Unidirectional type
- Low leakage current: 0.2  $\mu$ A at 25 °C
- Operating  $T_j$  max: 175 °C
- JEDEC registered package outline
- Resin meets UL94, V0
- Lead finishing: matte tin plating

## Complies with the following standards

- UL94, V0
- J-STD-020 MSL level 1
- J-STD-002, JESD 22-B102 E3 and MIL-STD-750, method 2026
- JESD-201 class 2 whisker test
- IPC7531 footprint and JEDEC registered package outline
- IEC 61000-4-4 level 4:
  - 4 kV
- IEC 61000-4-2, C = 150 pF, R = 330  $\Omega$  exceeds level 4:
  - 30 kV (air discharge)
  - 30 kV (contact discharge)

## Description

The SMC50J TVS series are designed to protect sensitive equipment against electrostatic discharges according to IEC 61000-4-2, MIL STD 883 Method 3015, and electrical overstress such as IEC 61000-4-4 and 5. They are used for surges below 5000 W 10/1000  $\mu$ s.

This planar technology makes it compatible with high-end equipment and SMPS where low leakage current and high junction temperature are required to provide reliability and stability over time.

### Product status link

[SMC50J5.0A](#), [SMC50J6.0A](#),  
[SMC50J6.5A](#), [SMC50J8.5A](#),  
[SMC50J10A](#), [SMC50J11A](#),  
[SMC50J12A](#), [SMC50J13A](#),  
[SMC50J14A](#), [SMC50J15A](#),  
[SMC50J16A](#), [SMC50J18A](#),  
[SMC50J20A](#), [SMC50J22A](#),  
[SMC50J23A](#), [SMC50J24A](#),  
[SMC50J26A](#), [SMC50J28A](#),  
[SMC50J30A](#), [SMC50J31A](#),  
[SMC50J33A](#), [SMC50J36A](#),  
[SMC50J40A](#), [SMC50J48A](#),  
[SMC50J58A](#), [SMC50J64A](#),  
[SMC50J70A](#), [SMC50J85A](#),  
[SMC50J100A](#).

# 1 Characteristics

Table 1. Absolute maximum ratings ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ )

Symbol	Parameter	Value	Unit	
$V_{PP}$	Peak pulse voltage	IEC 61000-4-2 (C = 150 pF, R = 330 $\Omega$ )		
		Contact discharge	30	kV
		Air discharge	30	
$P_{PP}$	Peak pulse power dissipation	$T_j$ initial = $T_{amb}$	5000	W
$T_{stg}$	Storage temperature range		-65 to +175	$^{\circ}\text{C}$
$T_j$	Operating junction temperature range		-55 to +175	$^{\circ}\text{C}$
$T_L$	Maximum lead temperature for soldering during 10 s		260	$^{\circ}\text{C}$

Figure 1. Electrical characteristics - parameter definitions

- $V_{RM}$  Maximum stand-off voltage
- $I_{RM}$  Maximum leakage current @  $V_{RM}$
- $V_R$  Stand-off voltage
- $I_R$  Leakage current @  $V_R$
- $V_{BR}$  Breakdown voltage @  $I_{BR}$
- $I_{BR}$  Breakdown current
- $V_{CL}$  Clamping voltage @  $I_{PP}$
- $I_{PP}$  Peak pulse current
- $R_D$  Dynamic resistance
- $V_F$  Forward voltage drop @  $I_F$
- $I_F$  Forward current
- $\alpha T$  Voltage temperature coefficient

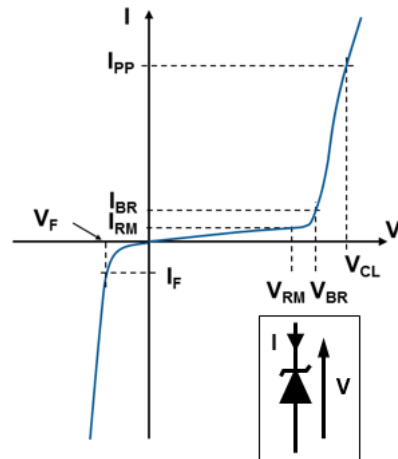
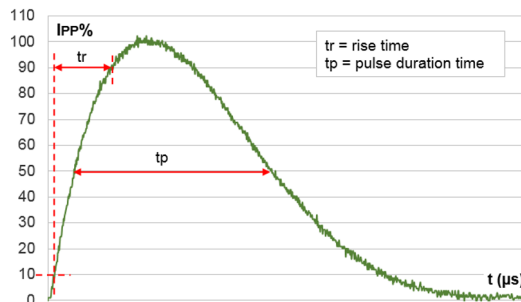


Figure 2. Pulse definition for electrical characteristics



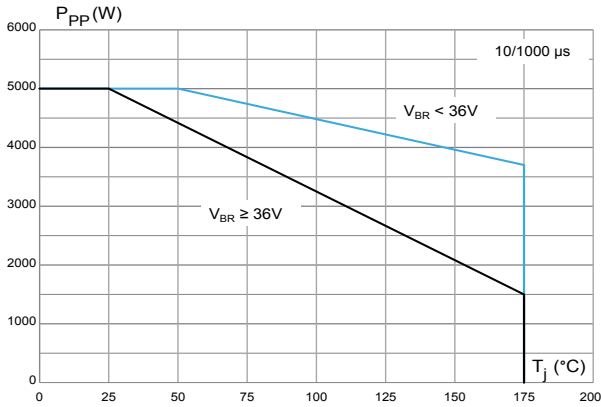
**Table 2. Electrical characteristics - parameter values ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)**

Type	$I_{RM}$ max at $V_{RM}$			$V_{BR}$ at $I_R$ <sup>(1)</sup>				10 / 1000 $\mu\text{s}$			8 / 20 $\mu\text{s}$			$\alpha T$
								$V_{CL}$ <sup>(2)(3)</sup>	$I_{PP}$	$R_D$	$V_{CL}$ <sup>(2)(3)</sup>	$I_{PP}$	$R_D$	
	25 $^{\circ}\text{C}$	85 $^{\circ}\text{C}$		Min.	Typ.	Max.		Max.		Max.	Max.		Max.	
	$\mu\text{A}$	$\mu\text{A}$	V	V	V	V	mA	V	A	m $\Omega$	V	A	m $\Omega$	$10^{-4}/^{\circ}\text{C}$
SMC50J5.0A	20	50	5.0	6.4	6.74	7.1	10	9.2	544	3.86	14.4	2136	3.59	5.7
SMC50J6.0A	20	50	6.0	6.7	7.05	7.4	10	10.3	486	5.97	14.7	2042	3.75	5.9
SMC50J6.5A	20	50	6.5	7.2	7.58	8	10	11.2	447	7.16	15.2	1986	3.84	6.1
SMC50J8.5A	20	50	8.5	9.4	9.9	10.4	1	14.4	348	11.5	18.6	1710	5.09	7.3
SMC50J10A	0.2	1	10	11.1	11.7	12.3	1	17	295	15.9	21.7	1505	6.64	7.8
SMC50J11A	0.2	1	11	12.3	13	13.7	1	18	275	15.6	24.2	1387	8.07	8.1
SMC50J12A	0.2	1	12	13.3	14	14.7	1	19.9	252	20.6	25.3	1309	8.63	8.3
SMC50J13A	0.2	1	13	14.4	15.2	16	1	21.5	233	23.6	27.2	1227	9.78	8.4
SMC50J14A	0.2	1	14	15.7	16.5	17.3	1	23.1	216	26.9	29	1151	10.9	8.6
SMC50J15A	0.2	1	15	16.7	17.6	18.5	1	24.4	205	28.8	32.5	1095	13.6	8.8
SMC50J16A	0.2	1	16	17.9	18.8	19.8	1	26	192	32.3	34.2	1040	14.8	9.0
SMC50J18A	0.2	1	18	20	21.1	22.2	1	29.2	171	40.9	39.3	950	19.2	9.2
SMC50J20A	0.2	1	20	22.2	23.4	24.6	1	32.4	155	50.3	42.8	876	22.1	9.4
SMC50J22A	0.2	1	22	24.4	25.7	27	1	35.5	141	60.3	48.3	815	27.7	9.6
SMC50J23A	0.2	1	23	25.7	27	28.4	1	37.8	135	69.6	49.2	784	28.3	9.6
SMC50J24A	0.2	1	24	26.7	28.1	29.5	1	38.9	129	72.9	50	760	28.8	9.6
SMC50J26A	0.2	1	26	28.9	30.4	31.9	1	42.1	119	85.7	53.5	715	32.3	9.7
SMC50J28A	0.2	1	28	31.1	32.7	34.3	1	45.4	110	100.9	59	675	39.0	9.8
SMC50J30A	0.2	1	30	33.2	35	36.8	1	48.4	103	112.6	64.3	640	45.8	9.9
SMC50J31A	0.2	1	31	34.2	36	37.8	1	50.2	100	124	65	626	46.3	9.9
SMC50J33A	0.2	1	33	36.7	38.6	40.5	1	53.3	94	136	69.7	593	52.4	10.0
SMC50J36A	0.2	1	36	40	42.1	44.2	1	58.1	86	162	76	550	61.6	10.0
SMC50J40A	0.2	1	40	44.4	46.7	49	1	64.5	78	199	84	511	73.0	10.1
SMC50J48A	0.2	1	48	53.2	56	58.8	1	77.4	65	286	100	444	99.1	10.3
SMC50J58A	0.2	1	58	64.6	68	71.4	1	93.6	53	419	121	381	139	10.4
SMC50J64A	0.2	1	64	71.1	74.8	78.6	1	103	47	447	133	353	164	10.4
SMC50J70A	0.2	1	70	77.9	82	86.1	1	113	42	640	146	345	186	10.5
SMC50J85A	0.2	1	85	95	100	105	1	137	32	1000	178	265	294	10.6
SMC50J100A	0.2	1	100	111	117	123	1	179	28	2000	212	227	419	10.7

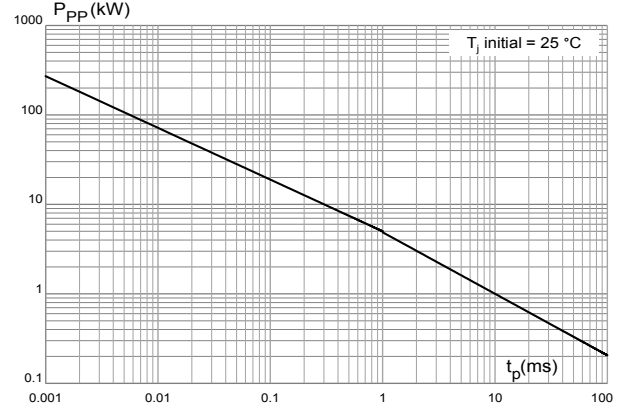
1. To calculate  $V_{BR}$  versus  $T_j$ :  $V_{BR}$  at  $T_j = V_{BR}$  at  $25\text{ }^{\circ}\text{C} \times (1 + \alpha T \times (T_j - 25))$
2. To calculate  $V_{CL}$  versus  $T_j$ :  $V_{CL}$  at  $T_j = V_{CL}$  at  $25\text{ }^{\circ}\text{C} \times (1 + \alpha T \times (T_j - 25))$
3. To calculate  $V_{CL}$  max versus  $I_{PP\text{appli}}$ :  $V_{CL\text{max}} = V_{CL} - R_D \times (I_{PP} - I_{PP\text{appli}})$  where  $I_{PP\text{appli}}$  is the surge current in the application

## 1.1 Characteristics (curves)

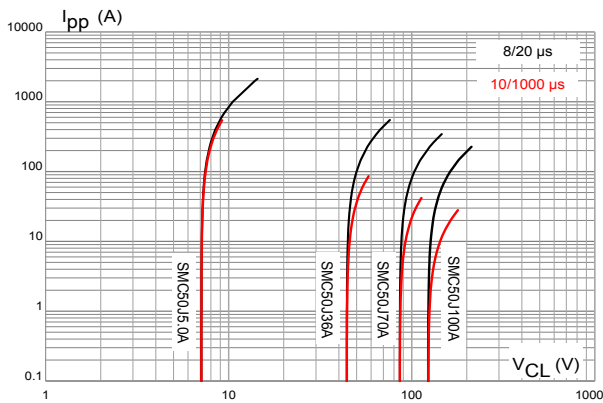
**Figure 3. Maximum peak power dissipation versus initial junction temperature**



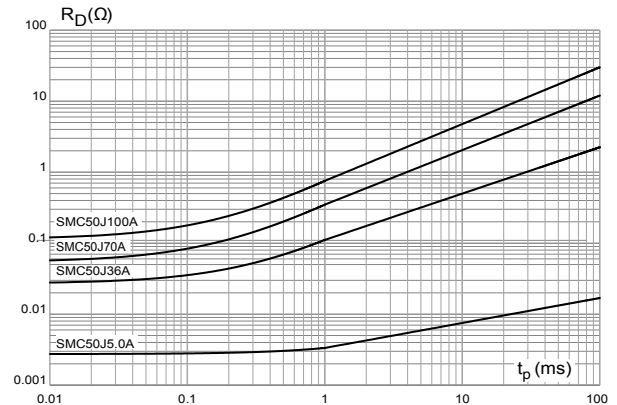
**Figure 4. Maximum peak pulse power versus exponential pulse duration**



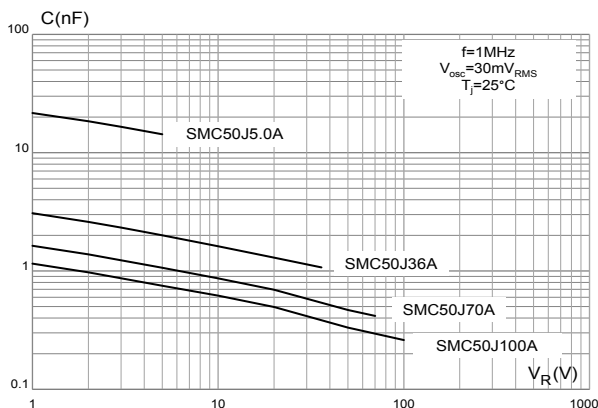
**Figure 5. Maximum peak pulse current versus clamping voltage**



**Figure 6. Dynamic resistance versus pulse duration**



**Figure 7. Junction capacitance versus reverse applied voltage (unidirectional type)**



**Figure 8. Leakage current versus junction temperature**

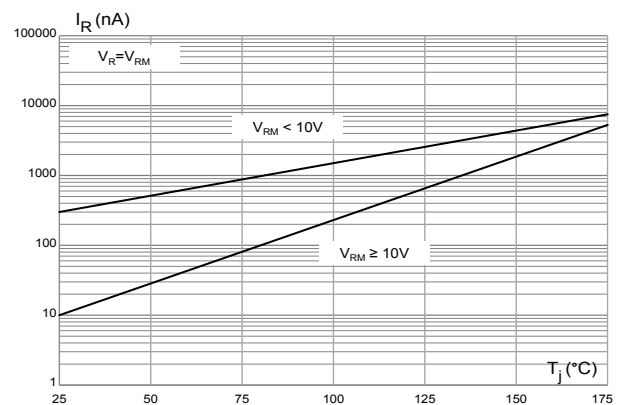


Figure 9. Peak forward voltage drop versus peak forward current

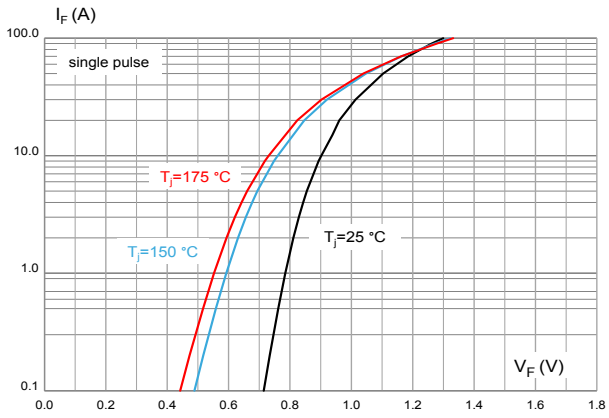


Figure 10. Thermal impedance junction to ambient versus pulse duration

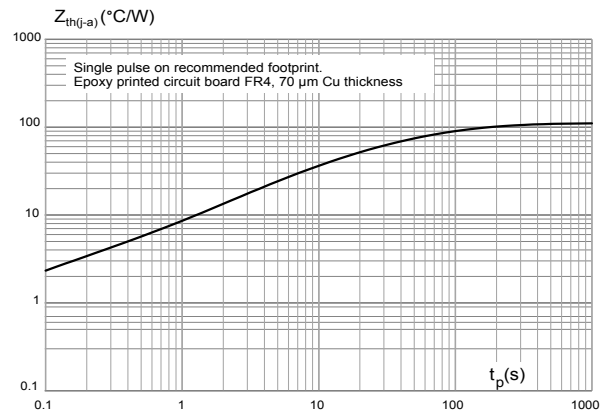
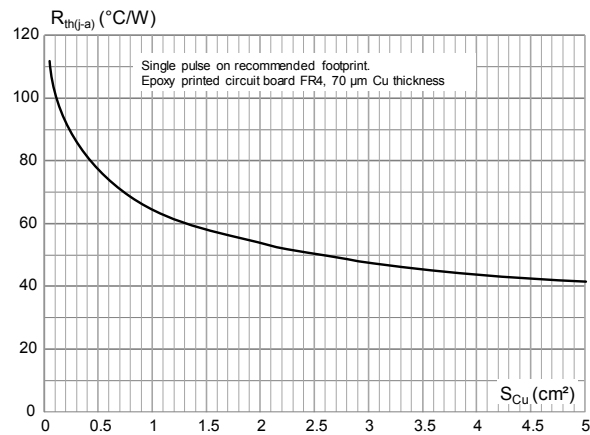


Figure 11. Thermal resistance junction to ambient versus copper area under each lead

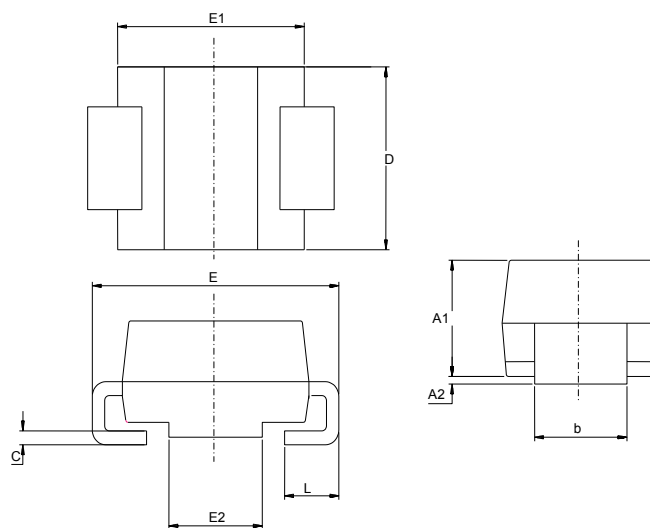


## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 2.1 SMC package information

**Figure 12. SMC package outline**



**Table 3. SMC package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	2.90	3.20	0.114	0.126
c	0.15	0.40	0.006	0.016
D	5.55	6.25	0.218	0.246
E	7.75	8.15	0.305	0.321
E1	6.60	7.15	0.260	0.281
E2	4.40	4.70	0.173	0.185
L	0.75	1.50	0.030	0.060

Figure 13. Footprint recommendation

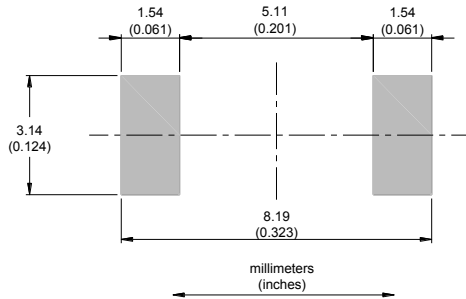


Figure 14. Marking layout

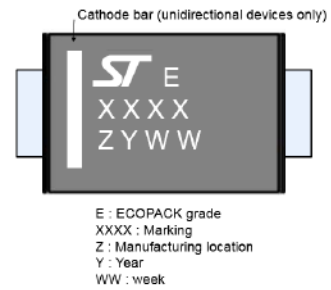
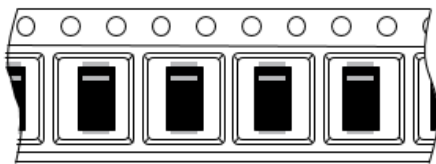


Figure 15. Package orientation in reel



Taped according to EIA-481  
Note: Pocket dimensions are not on scale  
Pocket shape may vary depending on package

Figure 16. Tape and reel orientation

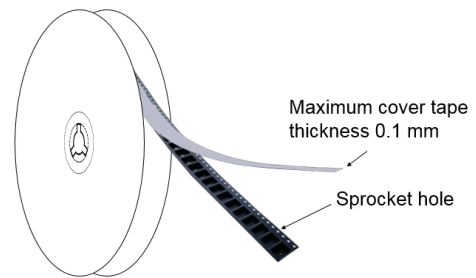


Figure 17. 13" reel dimension values (mm)

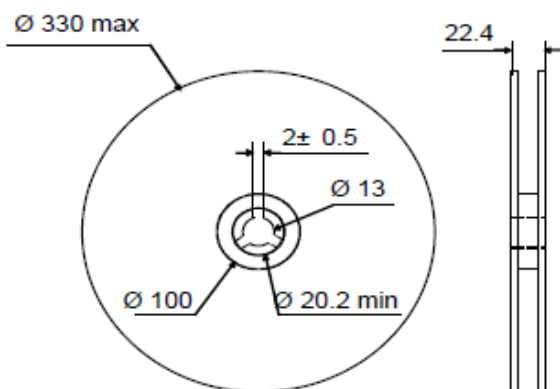


Figure 18. Inner box dimension values (mm)

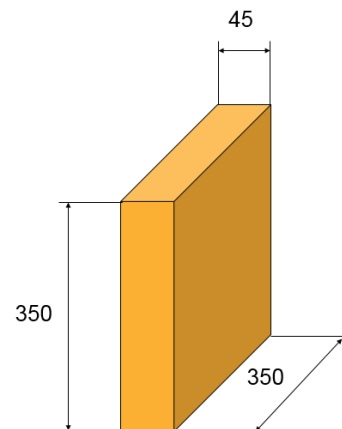
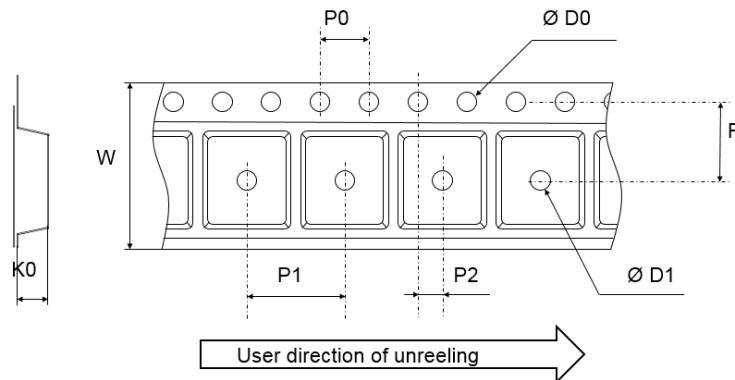


Figure 19. Tape outline



Note: Pocket dimensions are not on scale  
Pocket shape may vary depending on package

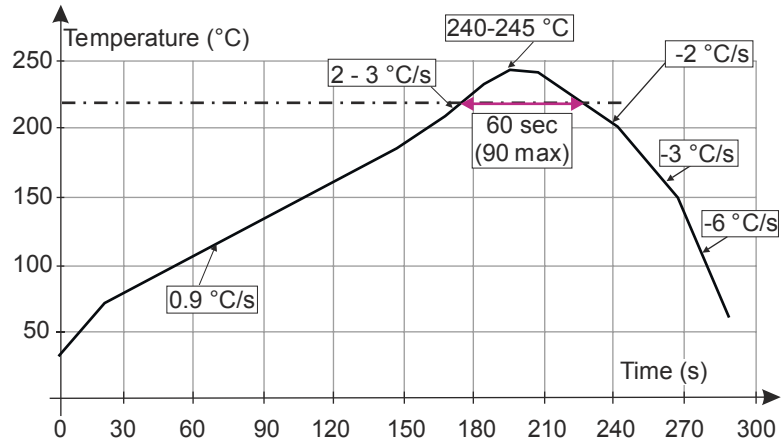
Table 4. Tape dimension values

Ref.	Dimensions		
	Millimeters		
	Min.	Typ.	Max.
D0	1.4	1.5	1.6
D1	1.5		
F	7.4	7.5	7.6
K0	2.39	2.49	2.59
P0	3.9	4.0	4.1
P1	7.9	8.0	8.1
P2	1.9	2.0	2.1
W	15.7	16	16.3



## 2.2 Reflow profile

Figure 20. ST ECOPACK recommended soldering reflow profile for PCB mounting



*Note:* Minimize air convection currents in the reflow oven to avoid component movement. Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020.

### 3 Ordering information

Table 5. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
SMC50JxxA <sup>(1)</sup>	See Table 6. Marking.	SMC	264 mg	2500	Tape and reel

1. Where xx is  $V_{RM}$ .

Table 6. Marking

Order code	Marking
SMC50J5.0A	EAI
SMC50J6.0A	EAK
SMC50J6.5A	EAL
SMC50J8.5A	EAP
SMC50J10A	EAS
SMC50J11A	EAU
SMC50J12A	EAW
SMC50J13A	EAY
SMC50J14A	EBA
SMC50J15A	EBC
SMC50J16A	EBE
SMC50J18A	EBI
SMC50J20A	EBM
SMC50J22A	EBO
SMC50J23A	EBP
SMC50J24A	EBQ
SMC50J26A	EBS
SMC50J28A	EBU
SMC50J30A	EBW
SMC50J31A	EBX
SMC50J33A	EBZ
SMC50J36A	ECC
SMC50J40A	ECG
SMC50J48A	ECO
SMC50J58A	ECY
SMC50J64A	EDE
SMC50J70A	EDK
SMC50J85A	EDZ
SMC50J100A	EEO

## Revision history

**Table 7. Document revision history**

Date	Revision	Changes
03-Nov-2021	1	Initial release.

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